

PATENT ASSIGNMENT

Electronic Version v1.1

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Wei-Hung Chang	11/23/2011
Chengming HE	11/23/2011
RECEIVING PARTY DATA	
Name:	SHENZHEN CHINA STAR OPTOELECTRONICS TECHNOLOGY CO., LTD.
Street Address:	No. 9-2, Tangming Road, Guangming New District
City:	Shenzhen, Guangdong
State/Country:	CHINA
Postal Code:	518132
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13375231
CORRESPONDENCE DATA	
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Correspondent Name:	B.Y.I.P., LTD.
Address Line 1:	P.O. Box 1484, General Post Office
Address Line 4:	Hong Kong, HONG KONG
ATTORNEY DOCKET NUMBER:	FR-1121-USPT
NAME OF SUBMITTER:	Charles Ho
Total Attachments: 2 source=Executed_Assignment_FR-1121-USPT (00056750)#page1.tif source=Executed_Assignment_FR-1121-USPT (00056750)#page2.tif	

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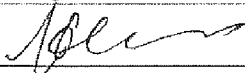
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PATENT
REEL: 027300 FRAME: 0495

ASSIGNMENT - Patent Application		Docket Number: FR-1121-USPT
Whereas, the Assignor, comprising the following named inventors:		
ASSIGNOR(s)/ INVENTOR(s)	CHANG, Wei-Hung	
made an invention entitled: THIN FILM TRANSISTOR ARRAY STRUCTURE AND MANUFACTURING METHOD THEREOF		
for which an application for Letters Patent of the United States: (Select one of the following):		
<input checked="" type="checkbox"/> is executed concurrently herewith <input type="checkbox"/> was filed in the U.S. Patent and Trademark Office on _____, as U.S. Patent Application Serial No.: _____		
ASSIGNEE (Full Name, Address and Country)	Shenzhen China Star Optoelectronics Technology Co., Ltd. No. 9-2, Tangming Road, Guangming New District, Shenzhen Guangdong 518132 China	
is desirous of acquiring our entire right, title and interest in and to said invention and the Letters Patent to be obtained therefor, Now, therefore, in consideration of the payment by Assignee to Assignor of a sum corresponding to One Dollar (\$1.00), and for other good and valuable consideration, the receipt of which is hereby acknowledged, Assignor, intending to be legally bound, hereby sells, assigns and transfers to Assignee, its successors and assigns, the full and exclusive right, title and interest in and to said invention, all applications for Letters Patent for said invention, including all divisions, continuations, and continuations-in-part thereof, all rights to claim priority based thereon, and all Letters Patent, including reissues, to be obtained therefor, including any and all foreign patent rights in this invention corresponding thereto. Assignor hereby warrants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this Assignment. Assignor agrees it shall be legally bound, upon request of the Assignee or its successors or assigns or a legal representative thereof, to supply all information and evidence of which the Assignor has knowledge or possession, relating to the making and practice of said invention, to testify in any legal proceeding relating thereto, to execute all instruments proper to patent the invention in the United States of America and foreign countries in the name of the Assignee, and to execute all instruments proper to carry out the intent of this instrument. In witness whereof, this Assignment is executed on the day indicated below.		

	Typed or Printed Name	Signature	Date
SIGNATURE	CHANG, Wei-Hung	x <i>Chang Wei-Hung</i>	x 2011.11.23

ASSIGNMENT - Patent Application		Docket Number: FR-1121-USPT
Whereas, the Assignor, comprising the following named inventors:		
ASSIGNOR(s)/ INVENTOR(s)	HE, Chengming	
made an invention entitled: THIN FILM TRANSISTOR ARRAY STRUCTURE AND MANUFACTURING METHOD THEREOF		
for which an application for Letters Patent of the United States: (Select one of the following):		
<input checked="checked" type="checkbox"/> is executed concurrently herewith <input type="checkbox"/> was filed in the U.S. Patent and Trademark Office on _____ as U.S. Patent Application Serial No.: _____		
ASSIGNEE (Full Name, Address and Country)	Shenzhen China Star Optoelectronics Technology Co., Ltd. No. 9-2, Tangming Road, Guangming New District, Shenzhen Guangdong 518132 China	
<p>is desirous of acquiring our entire right, title and interest in and to said invention and the Letters Patent to be obtained therefor,</p> <p>Now, therefore, in consideration of the payment by Assignee to Assignor of a sum corresponding to One Dollar (\$1.00), and for other good and valuable consideration, the receipt of which is hereby acknowledged, Assignor, intending to be legally bound, hereby sells, assigns and transfers to Assignee, its successors and assigns, the full and exclusive right, title and interest in and to said invention, all applications for Letters Patent for said invention, including all divisions, continuations, and continuations-in-part thereof, all rights to claim priority based thereon, and all Letters Patent, including reissues, to be obtained therefor, including any and all foreign patent rights in this invention corresponding thereto.</p> <p>Assignor hereby warrants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this Assignment.</p> <p>Assignor agrees it shall be legally bound, upon request of the Assignee or its successors or assigns or a legal representative thereof, to supply all information and evidence of which the Assignor has knowledge or possession, relating to the making and practice of said invention, to testify in any legal proceeding relating thereto, to execute all instruments proper to patent the invention in the United States of America and foreign countries in the name of the Assignee, and to execute all instruments proper to carry out the intent of this instrument.</p> <p>In witness whereof, this Assignment is executed on the day indicated below.</p>		

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SIGNATURE	HE, Chengming	x 	x 2011.11.23